12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20240326002.1
Qualification of RFAB using qualified Process Technology, Die Revision, and additional Assembly site options
Change Notification / Sample Request

Date: March 27, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240326002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV3011AMDBVREP	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240326002.1	PCN Date:	March 27, 2024
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, and additional Assembly site options		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	June 25, 2024	Estimated Sample Availability:	April 26, 2024*

***Sample requests received after April 26, 2024 will not be supported.**

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Materials
☒	Packing/Shipping/ Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology and additional Assembly site (TIPI) options for the device listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
TSMC-WF2	0.5DPDM	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Additionally, there will be a BOM options introduced for these devices:

	UTL2	TIPI
Mount Compound	SID#PZ0001	**8095733**
Mold Compound	SID#CZ0096	**4222198**

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-WF2	TS2	TWN	SAN JOSE
RFAB	**RFB**	**USA**	**Richardson**

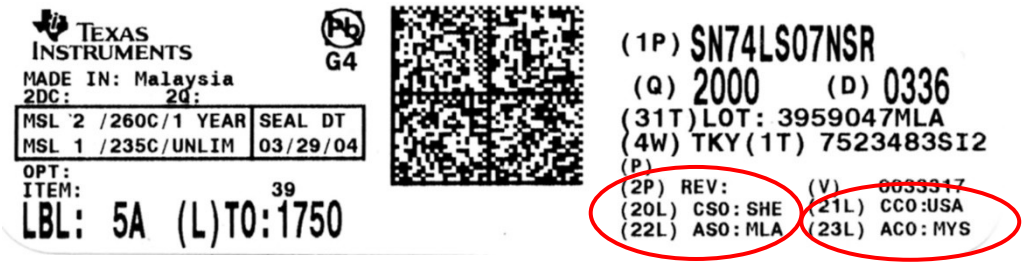
Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL2	NS2	THA	Bangpakong, Chachoengsao
TIPI	**PHI**	**PHL**	**Baguio City**

Sample product shipping label (not actual product label)



Product Affected:

TLV3011AMDBVREP

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Report

TLV3011AMDBVREP (Enhanced Product) Change Qualification
Approve Date 28-APRIL -2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV3011AMDBVREP	QBS Reference: TLV1805QDBVRQ1	QBS Reference: TLV3011AQDBVRQ1	QBS Reference: TLV3012AQDBVRQ1	QBS Reference: TLV3012AMDBVREP
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	1/77/0
HAST	A2	Biased HAST	130C/85%RH	250 Hours	-	-	-	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	192 Hours	-	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	1/45/0	-
HTSL	A6	High Temperature Storage Life	175C	2500 Hours	-	-	-	-	1/77/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	1/77/0

Type	#	Test Name	Condition	Duration	Qual Device: TLV3011AMDBVREP	QBS Reference: TLV1805QDBVRQ1	QBS Reference: TLV3011AQDBVRQ1	QBS Reference: TLV3012AQDBVRQ1	QBS Reference: TLV3012AMDBVREP
HTOL	B1	Life Test	150C	408 Hours	-	-	1/77/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	3/90/0	-	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device TLV3011AMDBVREP is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2110-034

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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